

### Description

The HSH150N02 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

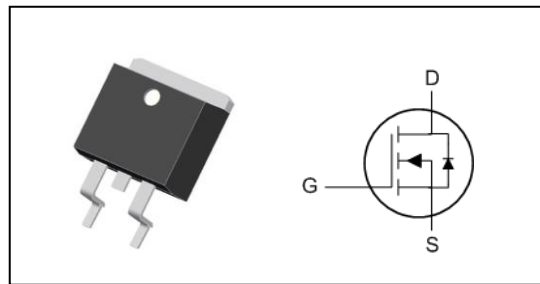
The HSH150N02 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Power Switching application
- Green Device Available
- Motion control application
- High efficiency synchronous rectification in SMPS

### Product Summary

$V_{DS}$	150	V
$R_{DS(ON),typ}$	12	$m\Omega$
$I_D$	120	A

### TO263 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	120	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	84	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	420	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	1010	mJ
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>3</sup>	300	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	60	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.55	$^\circ C/W$

## N-Ch 150V Fast Switching MOSFETs

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	150	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =60A	---	12	15	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	3	---	5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	3.2	---	Ω
Q <sub>g</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =120V, V <sub>GS</sub> =10V, I <sub>D</sub> =60A	---	135	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	29	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	48	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =75V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω I <sub>D</sub> =60A	---	30	---	ns
T <sub>r</sub>	Rise Time		---	39	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	75	---	
T <sub>f</sub>	Fall Time		---	55	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	---	5782	---	pF
C <sub>oss</sub>	Output Capacitance		---	569	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	318	---	

### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	120	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	420	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =60A, T <sub>J</sub> =25°C	---	---	1.1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =60A, dI/dt=100A/μs, T <sub>J</sub> =25°C	---	47	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	93	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.3mH
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



### Typical Characteristics

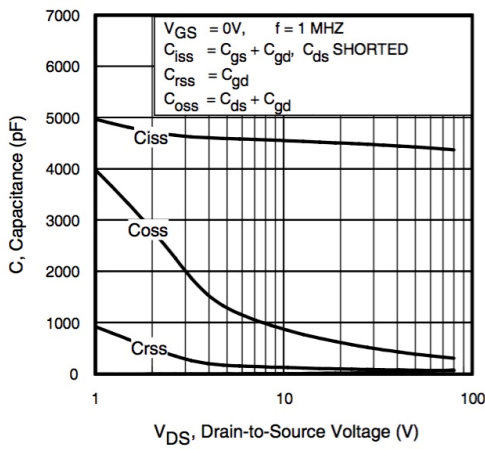


Fig.1 Typical Capacitance vs. Drain-Source Voltage

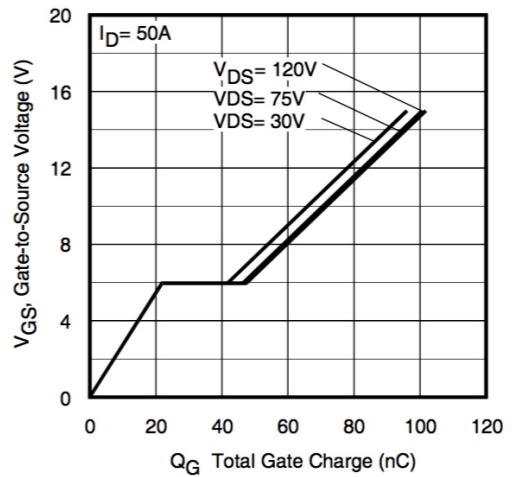


Fig.2 Typical Gate Charge vs. Gate-Source Voltage

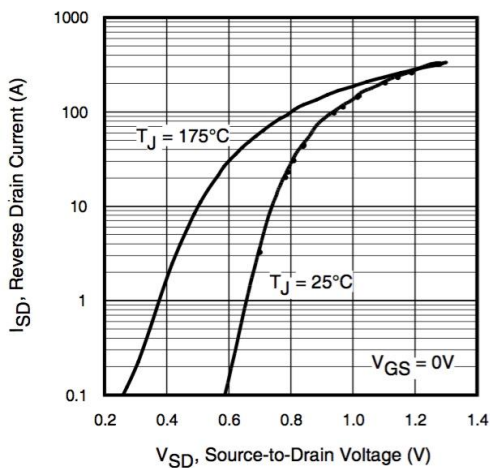


Fig.3 Typical Source-Drain Diode Forward Voltage

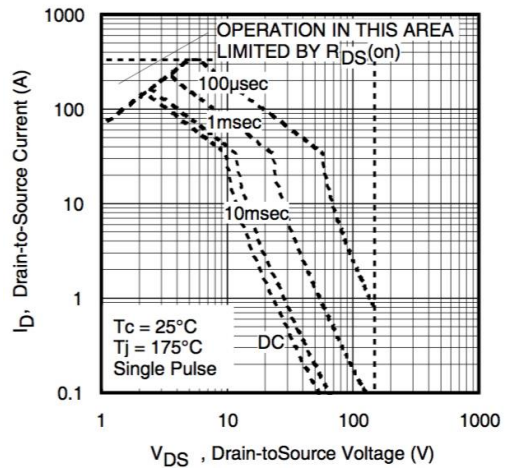


Fig.4 Maximum Safe Operating Area

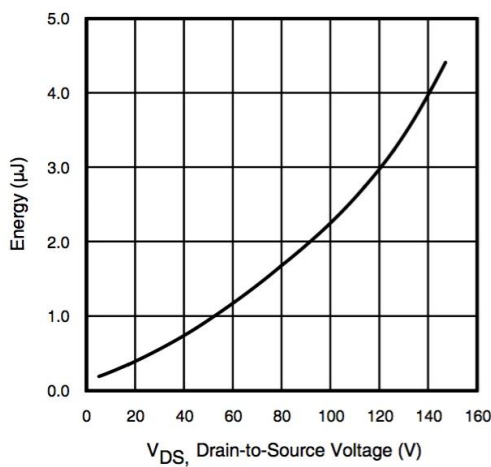


Fig.5 Typical Coss Stored Energy

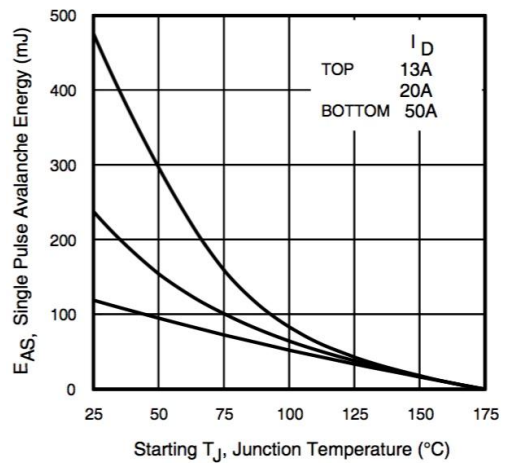
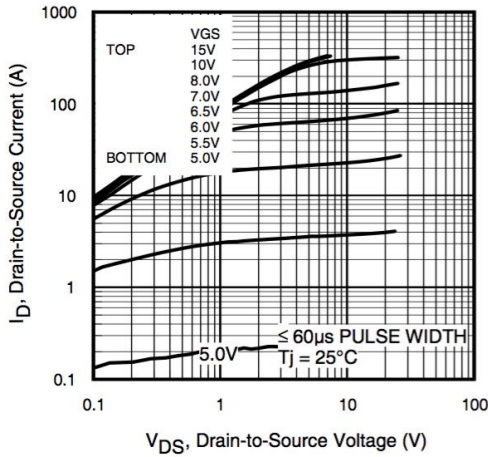
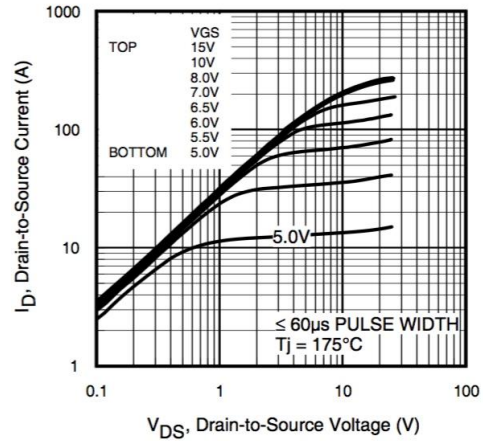


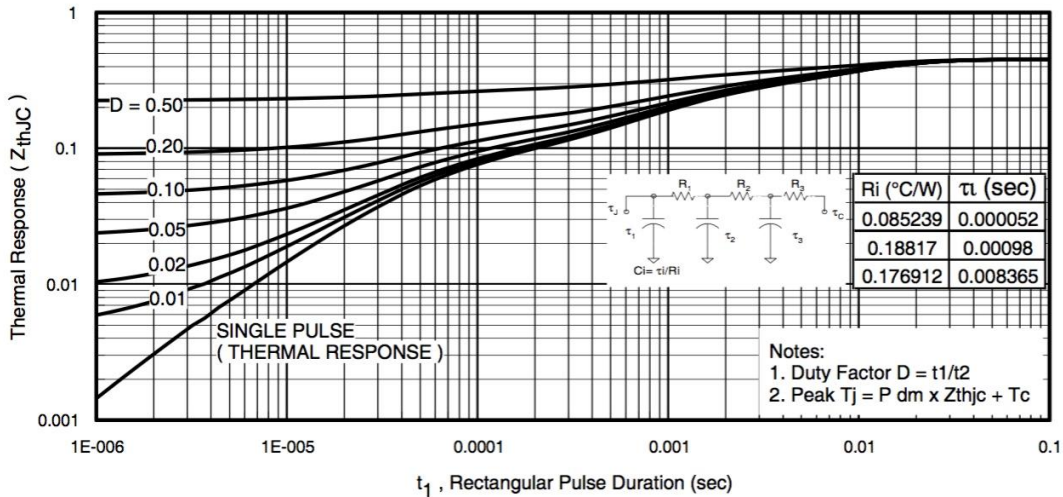
Fig.6 Maximum Avalanche Energy vs. Draincurrent



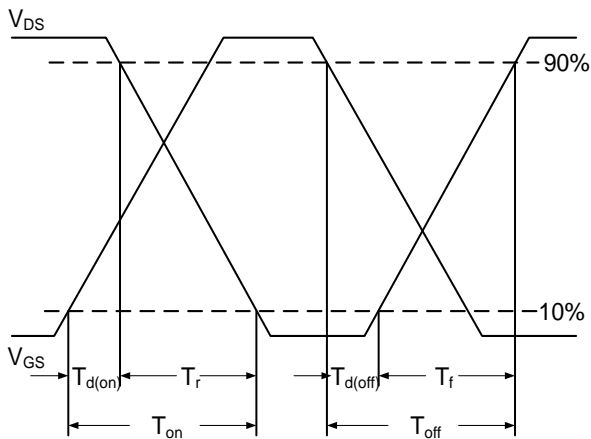
**Fig.7 VDS, Drain-to-Source Voltage(V)**



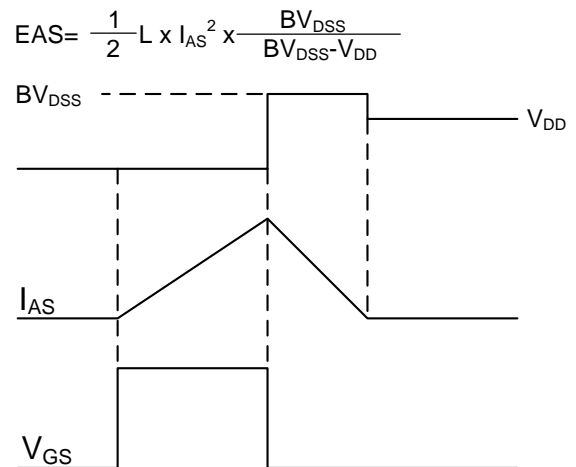
**Fig.8 VDS, Drain-to-Source Voltage(V)**



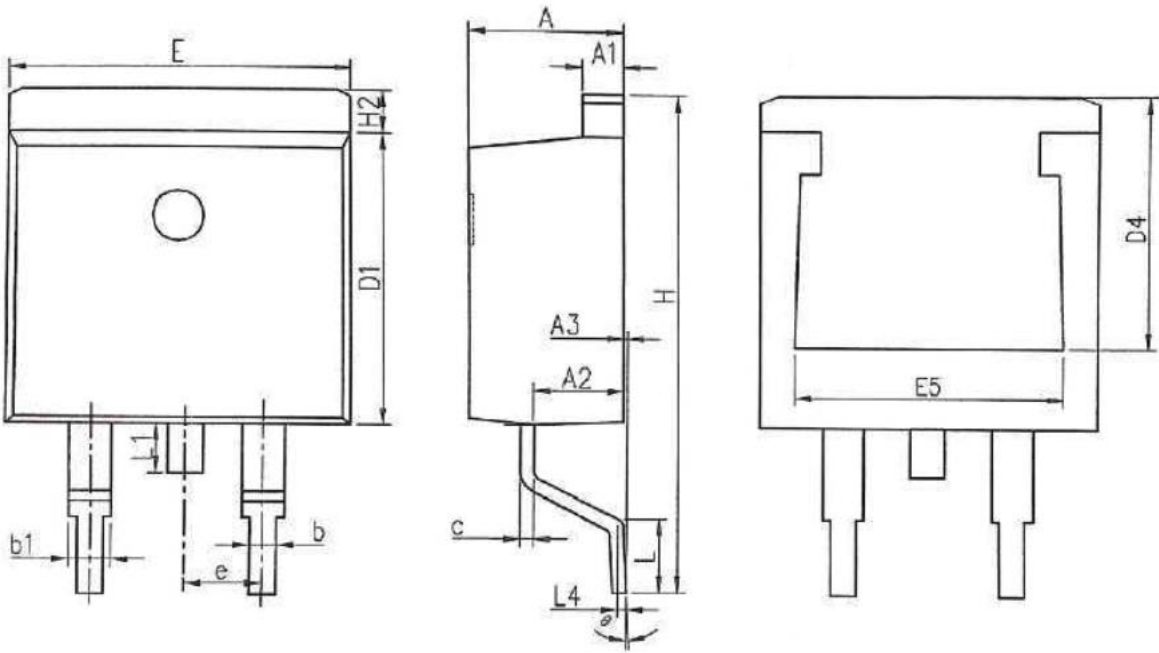
**Fig.9 Maximum Effective Transient Thermal Impedance, Junction-Case**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching**



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.370	4.770	0.172	0.188
A1	1.220	1.420	0.048	0.056
A2	2.200	2.890	0.087	0.114
A3	0.000	0.250	0.000	0.010
b	0.700	0.960	0.028	0.038
b1	1.170	1.470	0.046	0.058
c	0.300	0.530	0.012	0.021
D1	8.500	9.300	0.335	0.366
D4	6.600	-	0.260	-
E	9.860	10.36	0.388	0.408
E5	7.060	-	0.278	-
e	2.540 BSC		0.100 BSC	
H	14.70	15.70	0.579	0.618
H2	1.070	1.470	0.042	0.058
L	2.000	2.600	0.079	0.102
L1	1.400	1.750	0.055	0.069
L4	0.250 BSC		0.010 BSC	
Θ	0°	9°	0°	9°